

AEC/APC Symposium Asia 2025 SPONSORSHIP and Exhibition **November 25-26, 2025, Fukuoka, Japan**

Hidetaka Nishimura
Chairman, AEC/APC Symposium Asia 2025 Executive Committee
Renesas Electronics Corporation

Shunichi Shibuki
Chairman, AEC/APC Symposium Asia 2025 Program Committee
Sony Semiconductor Manufacturing Corporation

It is our great pleasure to announce that the 10th annual AEC/APC Symposium Asia 2025 will be held on November 25-26, 2025 at Fukuoka International Congress Center, FUKUOKA CONVENTION CENTER, Fukuoka, Japan which is sponsored by ISSM (International Symposium on Semiconductor Manufacturing). The program consists of keynote speeches, tutorial speeches, oral speeches, poster presentations and supplier exhibition. This year, the symposium puts the subtitle "Evolution of AECAPC through Fusion of Domain Knowledge and AI/ML".

AEC/APC Symposium Asia continues to contribute to the growth of the semiconductor industry through its infrastructure for networking, discussion, and information sharing among the world's professionals. We would like you to cooperate with us by supporting the 10th anniversary of AEC/APC Symposium Asia. Please see the benefit of AEC/APC Symposium Asia 2025 sponsorship.

Conference Overview

Date: November 25-26, 2025
Location: Fukuoka International Congress Center, FUKUOKA CONVENTION CENTER
2-1 Sekijo-machi, Hakata-ku, Fukuoka City 812-0032
TEL: 092-262-4111 FAX: 092-262-4701
<https://www.marinemesse.or.jp/eng/congress/access/>
Sponsored by: International Symposium on Semiconductor Manufacturing (ISSM)
Supported by: Japan Electronics and Information Technology Industries Association
(TBA) Semiconductor Equipment Association of Japan (SEAJ)
Semiconductor Equipment and Materials International (SEMI)
Dry Process Symposium (DPS)

About AEC/APC Symposium

AEC/APC symposium calls its annual conference in North America, Europe, and Asia. The suppliers of the device, the equipment, the material, the software, the sensor, and the metrology shall meet, and discuss the more intelligent and the higher productive manufacturing system in the conferences. The conference is held in Taiwan and Japan every other year. AEC/APC is called the core of the scientific manufacturing technology. The technology has created the extensive progress of the productivity improvement and the yield improvement in the semiconductor manufacturing area. The technology discussed in the conferences has been applied and used in the process technology of LCD, PV and Battery.

In Japan, the 10th conference is called in this year. Since 2007, the conference has discussed the scientific manufacturing technology using the data which can monitor the manufacturing equipment and the process conditions.

The symposium provides an excellent opportunity among the technical authorities from Japan and from out of Japan to share their knowledge and technologies in AEC/APC area. The symposium can also be a very good chance for the professionals of the process control industry such as semiconductor to meet and discuss.

Today, this area already forms the core part of the manufacturing engineering technology.

The role of this symposium is very important, since people can share the information and the directions of the process control improvement, the equipment productivity improvement, and the material source reduction for the future.

*AEC: Advanced Equipment Control, APC: Advanced Process Control

AEC/APC Symposium Asia Organization

Japan Executive Committee

| | | |
|-------|--------------------|---------------------------------|
| Chair | Hidetaka Nishimura | Renesas Electronics Corporation |
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Japan Program Committee

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| Chair | Shunichi Shibuki | Sony Semiconductor Manufacturing Corporation |
| Vice-Chair | Sumika Arima | University of Tsukuba |
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| | Koichi Tateishi | Azbil Corporation |
| | Akira Kagoshima | Hitachi High-Tech Corporation |
| | Osamu Ohishi | IBM Japan Digital Services Company |
| | Koh Horimoto | IBM Japan Digital Services Company |
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| | Hiroyuki Morinaga | KIOXIA Corporation |
| | Senichi Nishibe | KLA-Tencor Japan Ltd. |
| | Takayuki Kawagishi | KOKUSAI ELECTRIC CORPORATION |
| | Kenji Miyake | Office Miyake |
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| | Toshiya Hirai | Rapidus Corporation |
| | Tsuyoshi Miyatake | Renesas Electronics Corporation |
| | Tomoo Nakayama | Renesas Electronics Corporation |
| | Koichi Sakamoto | Tokyo Electron America, Inc. |
| | Hisato Tanaka | Tokyo Electron Ltd. |
| Kazutaka Nagashima | Toshiba Electronic Devices & Storage Corporation | |
| Tomoya Tanaka | Tower Partners Semiconductor Co., Ltd. | |
| Takayuki Matsumoto | United Semiconductor Japan Co., Ltd. | |

AEC/APC Symposium Asia Advisor

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| Advisor | Koji Maekawa | Addison Clear Wave Coatings Inc. |
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AEC/APC Symposium Asia 2025 Sponsorship Fee

| | Platinum | Gold | Silver | Bronze |
|--|----------|----------|----------|----------|
| Sponsorship Fee (Non-taxation) | ¥800,000 | ¥500,000 | ¥300,000 | ¥100,000 |
| AEC/APC Symposium Asia Complimentary Ticket(s) (Free) | | | | |
| Free ticket(s) for AEC/APC Symposium Asia (Tutorial session excluded) | 12 | 7 | 4 | 1 |
| AEC/APC Symposium Asia Website | | | | |
| Company logo placed on homepage | Yes | Yes | Yes | Yes |
| Company logo placed on right-hand side of website | Upper | Middle | Lower | Lower |
| Link to company homepage | Yes | Yes | Yes | Yes |
| AEC/APC Symposium Asia Proceedings (Download) & Brochure | | | | |
| Recognition of sponsorship in meeting materials along with company logo and link to corporate website (User would need to have Internet access when viewing the proceedings) | Upper | Middle | Lower | Lower |
| Company logo printed in color on the brochure on site | Upper | Middle | Lower | Lower |
| AEC/APC Symposium Asia Screen at site | | | | |
| Company logo on the screen of interval | Upper | Middle | Lower | Lower |
| Company logo poster at the Symposium Room | Upper | Middle | Lower | Lower |
| List | | | | |
| Registrant List (Name, Affiliation, email. Only who accepted to provide to the sponsors.) | ○ | ○ | × | × |

★AEC/APC Symposium Asia 2025 Exhibit Fee

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|---|----------|
| Exhibit fee (1 booth) applied with any of above sponsorship (10% tax to be added) | ¥120,000 |
| Exhibit only fee (10% tax to be added) | ¥150,000 |

AEC/APC Symposium Asia 2025 – Registration Fee

| Category | | JP Yen (Tax included) |
|----------------------------------|---|------------------------------|
| Regular | Early bird (October 24, 2025 due) | ¥33,000 |
| | Regular (On and after October 25, 2025) | ¥39,600 |
| Student | The registration fee for student speakers is waived. Please contact to the secretariat | ¥5,500 |
| Bulk | (Group 5) | ¥145,000(¥29,000 per person) |
| | (Group 10) | ¥264,000(¥26,400 per person) |
| Sponsors (Complimentary tickets) | The registration information for the complimentary ticket(s) will be provided separately. | |

The above registration fee includes 2-day lecture sessions, networking reception on November 25, lunch on November 26, and online proceedings.

Contact:

AEC/APC Symposium Asia 2025 Office/C/O Semiconductor Portal, Inc.

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